**Product data sheet** 

## 1. General description

Silicon Carbide Schottky diode in a 2-lead TO247-2L plastic package, designed for high frequency switched-mode power supplies.





### 2. Features and benefits

- · Extremely fast reverse recovery time
- Low figure of merit (Q<sub>C</sub>\*V<sub>F</sub>)
- · Highly stable switching performance
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Applications

- · Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- · LED / OLED TV
- Motor Drives

### 4. Quick reference data

### Table 1. Quick reference data

Table II di	uick reference data						
Symbol	Parameter	Conditions	Values			Unit	
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage			12	200		V
I <sub>F(AV)</sub>	average forward current	$δ$ = 0.5 ; square-wave pulse; $T_{mb}$ ≤ 123 °C; Fig. 1; Fig. 2; Fig. 3	15		А		
T <sub>j</sub>	junction temperature		175		°C		
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.45	1.7	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.95	2.3	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>		-	2.1	2.5	V
Dynamic characteristics							
Q <sub>r</sub>	recovered charge	$I_F = 15 \text{ A}$ ; $dI_F/dt = 500 \text{ A/µs}$ ; $V_R = 400 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7		-	35	-	nC

# 5. Pinning information

**Table 2. Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		V 14 A
2	А	anode		K — A 001aaa020
mb	mb	mounting base; connected to cathode	K A TO247-2L	

## 6. Ordering information

### **Table 3. Ordering information**

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D151200W	TO247-2L	WNSC2D151200WQ	Tube	30	TO247L-2L	10-Nov-2020

## 7. Marking

#### Table 4. Marking codes

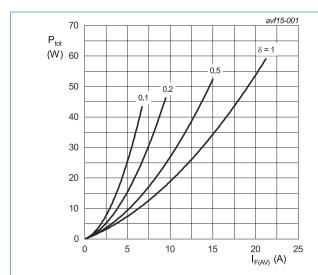
Type number	Marking codes
WNSC2D151200W	WNSC2D
	151200W

## 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		1200	V
$V_{RWM}$	crest working reverse voltage		1200	V
$V_R$	reverse voltage	DC	1200	V
I <sub>F(AV)</sub>	average forward current	$δ$ = 0.5; square-wave pulse; $T_{mb} \le 123$ °C; Fig. 1; Fig. 2; Fig. 3	15	А
I <sub>FRM</sub>	repetitive peak forward current	$δ = 0.5$ ; $t_p = 25 \mu s$ ; $T_{mb} \le 123 °C$ ; square-wave pulse	30	А
I <sub>FSM</sub>	non-repetitive peak	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	102	Α
	forward current	$t_p$ = 10 μs; $T_{j(init)}$ = 25 °C; square-wave pulse	950	Α
l <sup>2</sup> t	I <sup>2</sup> t for fusing	sine-wave pulse; $T_{j(init)}$ = 25 °C; $t_p$ = 10 ms	52	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature		-55 to 175	°C
T <sub>j</sub>	junction temperature		175	°C



$$\begin{split} I_{\text{F(AV)}} &= I_{\text{F(RMS)}} \times \sqrt{\delta} \\ V_{\text{o}} &= 1.087 \text{ V; } R_{\text{s}} = 0.0801 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

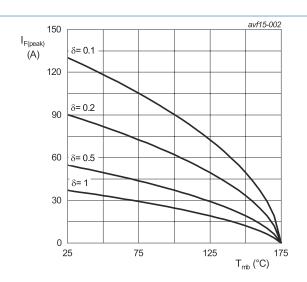
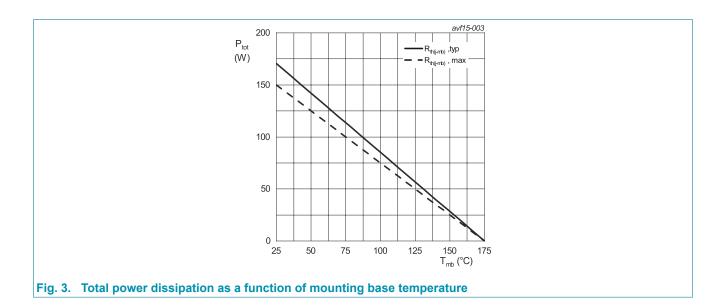


Fig. 2. Current derating as a function of mounting base temperature



### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4	-	0.88	1	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	40	-	K/W

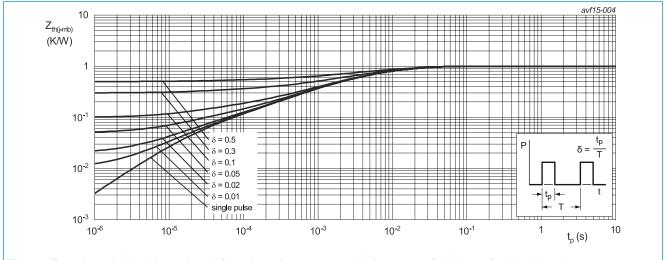
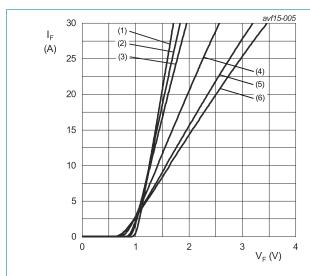


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Characteristics

Table 7 Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics					'
$V_{F}$	forward current	I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>	-	1.45	1.7	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>	-	1.95	2.3	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>	-	2.1	2.5	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 1200 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	5	150	μA
		V <sub>R</sub> = 1200 V; T <sub>j</sub> = 175 °C; <u>Fig. 6</u>	-	80	-	μA
Dynamic	characteristics					
Q <sub>r</sub>	recovered charge	$I_F = 15 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	35	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C	-	700	-	pF
		f = 1 MHz; V <sub>R</sub> = 400 V; T <sub>j</sub> = 25 °C	-	65	-	pF
		f = 1 MHz; V <sub>R</sub> = 800 V; T <sub>j</sub> = 25 °C	-	48	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	$I_R = 4.7 \text{ A}$ ; L = 10 mH; $T_{j(init)} = 25 \text{ °C}$	110	-	-	mJ



 $V_o = 1.087 \text{ V}; R_s = 0.0801 \Omega$ 

(1)  $T_j = -55$  °C; typical values

(2) T<sub>j</sub> = 0 °C; typical values

(3) T<sub>j</sub> = 25 °C; typical values (4) T<sub>j</sub> = 100 °C; typical values (5) T<sub>j</sub> = 150 °C; typical values

(6) T<sub>i</sub> = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

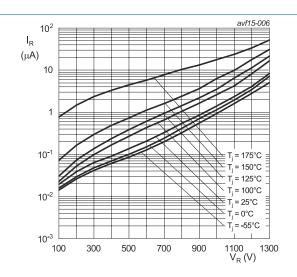


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

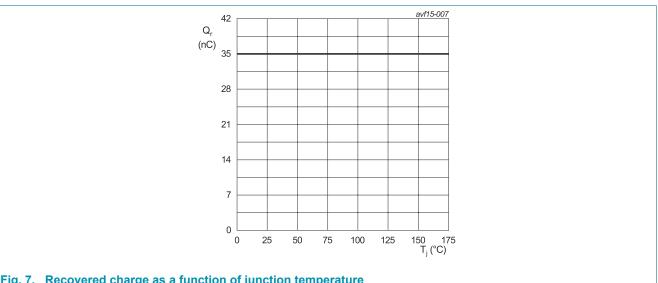
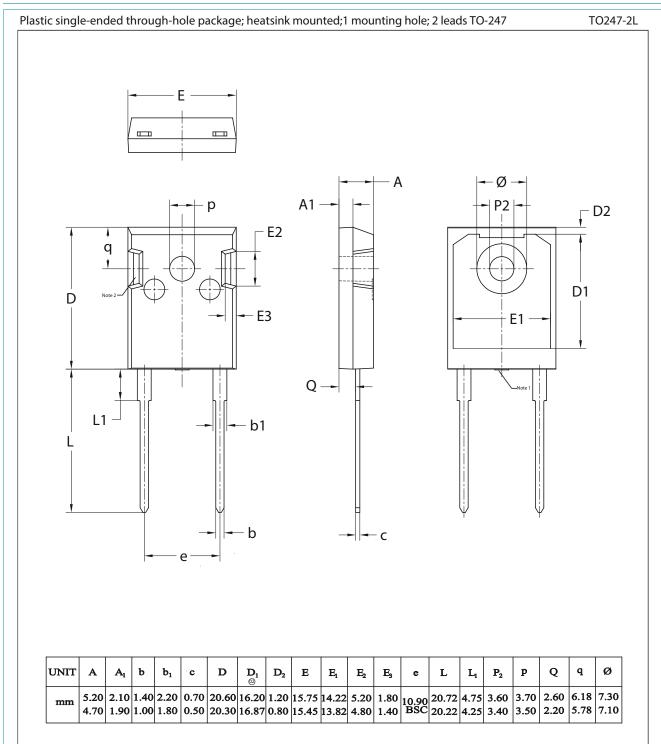


Fig. 7. Recovered charge as a function of junction temperature

## 11. Package outline



#### Note:

- 1. Mold resin protrusion max 0.127mm.
- 2. Metal exposed with Sn plating.

### 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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